

# SID

Factory: Rot am See

Article:

554

ML8

Provided:

Kracht, Enrico

Customer:

Date:

29.09.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	123		2		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3		
		35	L2			
A-RS-FR4-ML-0.51mm-035+035-TG150-HF	50200644	510		4	A01	
		35	L3			
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	105		5		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		6		
		35	L4			
A-RS-FR4-ML-0.51mm-035+035-TG150-HF	50200644	510		7	A02	B00
		35	L5			
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	105		8		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		9		
		35	L6			
A-RS-FR4-ML-0.51mm-035+035-TG150-HF	50200644	510		10	A03	
		35	L7			
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	123		11		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		12		
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	13		

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

2232 µm

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